

## Surface Mount Ultrafast Rectifier



DO-214AB (SMC)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

### FEATURES

- Low profile package
- Ideal for automated placement
- Oxide planar chip junction
- Ultrafast recovery times for high frequency
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: For definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)

### TYPICAL APPLICATIONS

For use in secondary rectification, and freewheeling for ultrafast switching speeds of AC/AC and DC/DC converters in high temperature conditions for both consumer and automotive applications.

### MECHANICAL DATA

**Case:** DO-214AB (SMC)

Molding compound meets UL 94 V-0 flammability rating Base P/N-M3 - halogen-free, RoHS-compliant, and commercial grade

**Terminals:** Matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 suffix meets JESD 201 class 2 whisker test

**Polarity:** Color band denotes cathode end

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	3.0 A
$V_{RRM}$	100 V, 150 V, 200 V
$I_{FSM}$	80 A
$t_{rr}$	25 ns
$V_F$ at $I_F = 3.0$ A	0.75 V
$T_J$ max.	175 °C
Package	DO-214AB (SMC)
Diode variations	Single die

MAXIMUM RATINGS ( $T_A = 25$ °C unless otherwise noted)					
PARAMETER	SYMBOL	UH3B	UH3C	UH3D	UNIT
Device marking code		HB	HC	HD	
Maximum repetitive peak reverse voltage	$V_{RRM}$	100	150	200	V
Maximum average forward rectified current (fig. 1)	$I_{F(AV)}^{(1)}$	2.5			A
	$I_{F(AV)}^{(2)}$	3.0			
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	$I_{FSM}$	80			A
Operating junction and storage temperature range	$T_J, T_{STG}$	-55 to +175			°C

#### Notes

(1) Free air, mounted on recommended copper pad area

(2) Units mounted on PCB with 0.31" x 0.31" (8.0 mm x 8.0 mm) copper pad area

ELECTRICAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	I <sub>F</sub> = 1.5 A	T <sub>A</sub> = 25 °C	V <sub>F</sub> <sup>(1)</sup>	0.85	-	V
	I <sub>F</sub> = 3.0 A			0.95	1.05	
	I <sub>F</sub> = 1.5 A	T <sub>A</sub> = 125 °C		0.65	-	
	I <sub>F</sub> = 3.0 A			0.75	0.90	
Reverse current	Rated V <sub>R</sub>	T <sub>A</sub> = 25 °C	I <sub>R</sub> <sup>(2)</sup>	-	5	μA
		T <sub>A</sub> = 125 °C		15	100	
Maximum reverse recovery time	I <sub>F</sub> = 0.5 A, I <sub>R</sub> = 1.0 A, I <sub>rr</sub> = 0.25 A	T <sub>A</sub> = 25 °C	t <sub>rr</sub>	14	25	ns
Typical reverse recovery time	I <sub>F</sub> = 1.0 A, dI/dt = 50 A/μs, V <sub>R</sub> = 30 V, I <sub>rr</sub> = 0.1 I <sub>RM</sub>			23	40	
Typical softness factor (t <sub>b</sub> /t <sub>a</sub> )		T <sub>A</sub> = 125 °C	S	0.2	-	
Typical reverse recovery current	I <sub>F</sub> = 3.0 A, dI/dt = 200 A/μs, V <sub>R</sub> = 200 V		I <sub>RM</sub>	5.0	7.0	A
Typical stored charge			Q <sub>rr</sub>	60	-	nC
Typical junction capacitance			4.0 V, 1 MHz	C <sub>J</sub>	42	-

### Notes

- (1) Pulse test: 300 μs pulse width, 1 % duty cycle
- (2) Pulse test: Pulse width ≤ 40 ms

THERMAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise noted)					
PARAMETER	SYMBOL	UH3B	UH3C	UH3D	UNIT
Typical thermal resistance	R <sub>θJA</sub> <sup>(1)</sup>	95			°C/W
	R <sub>θJM</sub> <sup>(1)</sup>	12			

### Note

- (1) Free air, mounted on recommended copper pad area. Thermal resistance R<sub>θJA</sub> - junction to ambient, R<sub>θJM</sub> - junction to mount

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
UH3D-M3/57T	0.236	57T	850	7" diameter plastic tape and reel
UH3D-M3/9AT	0.236	9AT	3500	13" diameter plastic tape and reel

### RATINGS AND CHARACTERISTICS CURVES (T<sub>A</sub> = 25 °C unless otherwise noted)

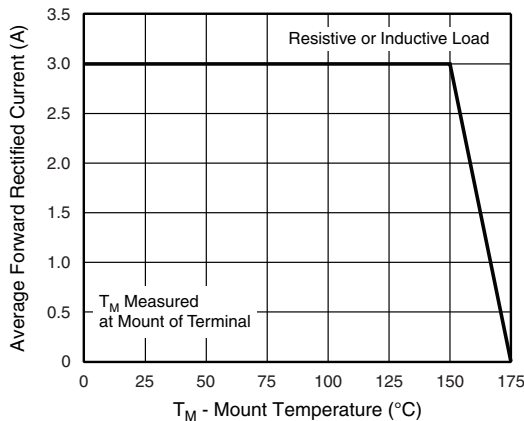


Fig. 1 - Maximum Forward Current Derating Curve

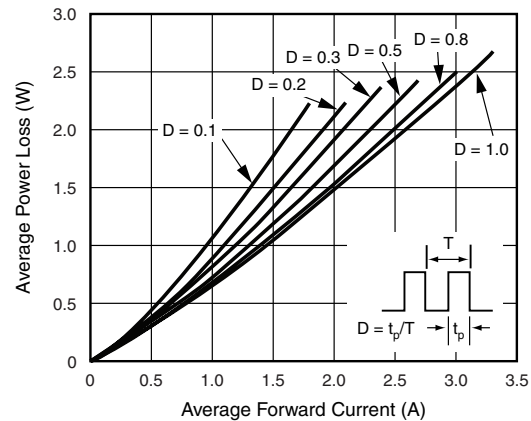


Fig. 2 - Forward Power Loss Characteristics

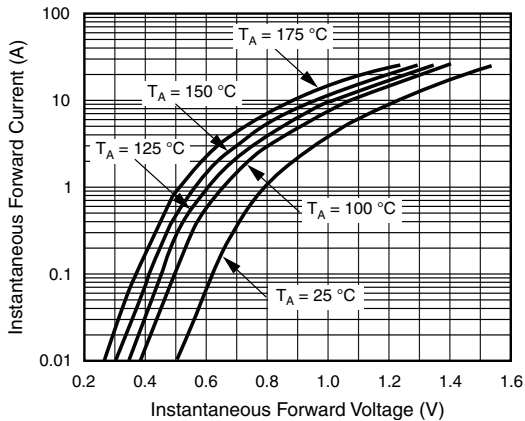


Fig. 3 - Typical Instantaneous Forward Characteristics

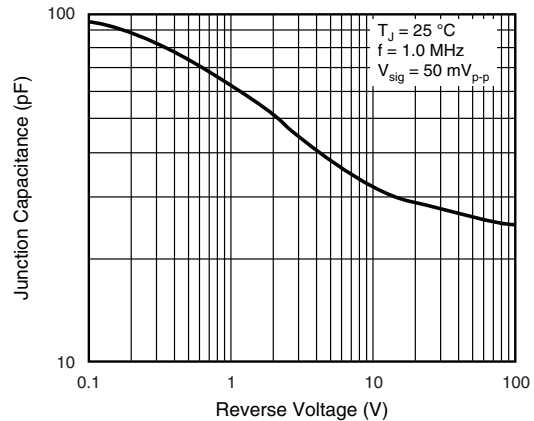


Fig. 5 - Typical Junction Capacitance

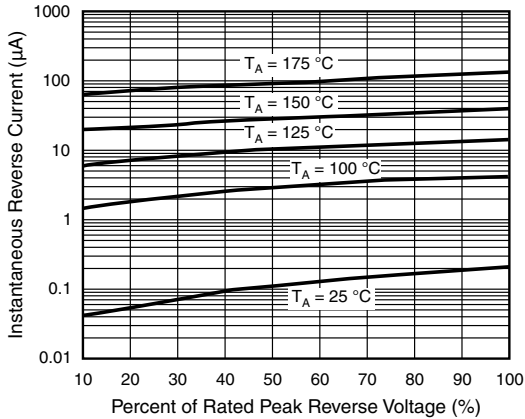


Fig. 4 - Typical Reverse Characteristics

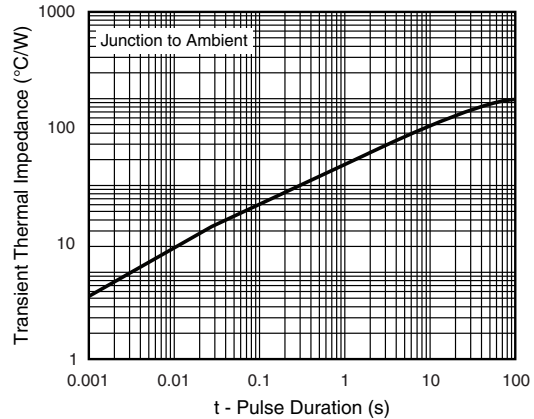
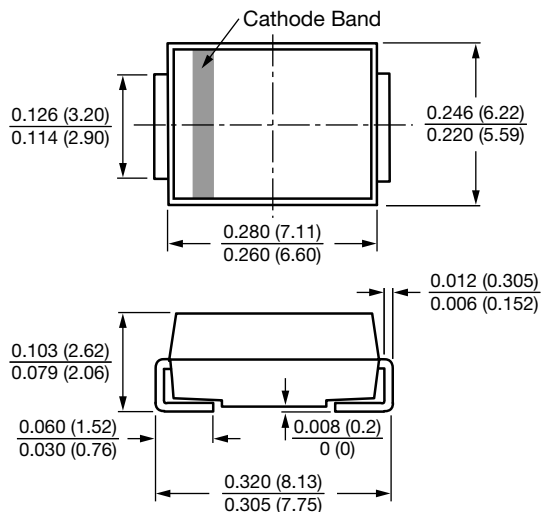


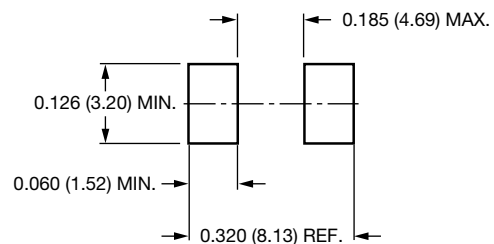
Fig. 6 - Typical Transient Thermal Impedance

## PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

### DO-214AB (SMC)



### Mounting Pad Layout





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